CLAIMS

1. A method for producing a mixture containing a compound obtained by reacting a compound represented by the following formula (1) with a compound represented by the following formula (2-1) and/or a compound represented by the following formula (2-2), wherein,

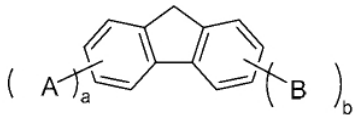
($\beta1+\beta2)/\alpha$ is 1.8 or more and 2.1 or less, wherein

α is the number of moles of the compound represented by the formula (1),

$\beta1$ is the number of moles of the compound represented by the formula (2-1), and

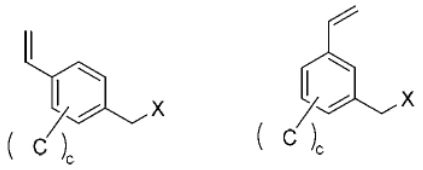
$\beta2$ is the number of moles of the compound represented by the formula (2-2), and

an amount of residual halogen in the mixture is 1 to 1,000 ppm:



(1)

in the above formula (1), A and B each represent a hydrogen atom or a hydrocarbon group having 1 to 5 carbon atoms, and a and b each represent an integer of 1 to 4,



(2-1) (2-2)

in the above formula (2-1), C represents a hydrogen atom or a hydrocarbon group having 1 to 5 carbon atoms, X represents a halogen element, and c represents an integer of 1 to 4,

in the above formula (2-2), C represents a hydrogen atom or a hydrocarbon group having 1 to 5 carbon atoms, X represents a halogen element, and c represents an integer of 1 to 4.

2. The method for producing the mixture according to claim 1, wherein ($\beta1+\beta2)/\alpha$ is 1.8 or more and 1.95 or less.

3. The method for producing the mixture according to claim 1 for use in a printed

wiring board.

4. The method for producing the mixture according to claim 1, wherein a cured product thereof has a dielectric dissipation factor of 0.0016 or less at a frequency of 10 GHz measured at 25°C.

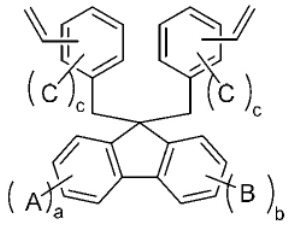
5. The method for producing the mixture according to claim 1, wherein β1/β2 is 0.5 to 25.

6. The method for producing the mixture according to claim 1, wherein β1/β2 is 0.8 to 3.0.

7. A method for producing a curable resin composition comprising the mixture obtained by the method according to claim 1.

8. A method for producing a cured product obtained by curing the mixture obtained by the method according to any one of claims 1 to 6 or the curable resin composition obtained by the method according to claim 7.

9. A mixture comprising a compound represented by the following formula (3), wherein an amount of residual halogen in the mixture is 1 to 1,000 ppm, and a cured product thereof has a dielectric dissipation factor of 0.0016 or less at a frequency of 10 GHz measured at 25°C,



(3)

in the above formula (3),

A and B each represent a hydrogen atom or a hydrocarbon group having 1 to 5 carbon atoms, and a and b each represent an integer of 1 to 4,

C represents a hydrogen atom or a hydrocarbon group having 1 to 5 carbon atoms, and

c represents an integer of 1 to 4.

10. A curable resin composition comprising the mixture according to claim 9.

11. A cured product obtained by curing the mixture according to claim 9 or the curable resin composition according to claim 10.